Intel Xeon (X14) | 2U Rackmount | Server

Supermicro SYS-222HA-TN

Intel Xeon (X14) · 2U Rackmount · Liquid Cooling Server

Specifications reproduced from the official Supermicro product page, as of 17 Nov 2026. Taknet Systems (Thailand) is a Supermicro Authorized Distributor.



Form Factor	**2U Rackmount**
CPU	**Intel® Xeon® 6900 Series processors with P-cores and Intel Xeon 6+ processors**
GPU	**Up to 4 double-width or 8 single-width GPUs**
Memory	**Max Memory (1DPC): Up to 6TB 8800MT/s ECC DDR5 MRDIMM (P-core only)**

Key Features

- Dual Intel® Xeon® 6900-Series Processors with P-cores and Xeon 6+ processors up to 500W
- Up to 24 DIMMs supporting up to 6TB 6400MT/s DDR5 RDIMM or 6TB 8800MT/s DDR5 MRDIMM
- Optional PCIe slot configurations up to 8 PCIe 5.0 x8 or 4 PCIe 5.0 x16 slots with support for double-width GPU/Accelerator cards
- Flexible networking options with up to 2 AIOM networking slots (OCP NIC 3.0 compatible)
- 8x 2.5" hot-swap NVMe/SATA/SAS drive bays with optional configurations for 16x/24x 2.5" hot-swap NVMe/SAS/SATA drive bays; 2x internal M.2 NVMe drive slots; Optional RAID support via storage add-on card

Form Factor	2U Rackmount
Platform	Intel Xeon (X14)
CPU	Dual Socket BR (LGA-7529) Intel® Xeon® 6900 Series processors with P-cores and Intel Xeon 6+ processors
Max GPU Count	Up to 4 double-width or 8 single-width GPUs
Supported GPU	NVIDIA PCIe: H100 NVL, A16, L4, L40S, NVIDIA RTX PRO™ 4500 Blackwell, NVIDIA RTX PRO™ 6000 Blackwell Max-Q Workstation Edition, RTX 5000 Ada
Memory	Slot Count: 24 DIMM slots Max Memory (1DPC): Up to 6TB 8800MT/s ECC DDR5 MRDIMM (P-core only)
Drive Bays	Default: Total 8 bays8 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bays
Fans	Up to 6 counter-rotating 60x60x56mm Fan(s)

Power Supply	2x 2600W Redundant (1 + 1) Titanium Level (96%) Hot-plug power supplies

Full Specifications — SYS-222HA-TN

Product SKUs

Part numbers	SYS-222HA-TN

Motherboard

Motherboard	Super X14DBM-AP

Processor

CPU	Dual Socket BR (LGA-7529) Intel® Xeon® 6900 Series processors with P-cores and Intel Xeon 6+ processors
Core Count	P-cores: Up to 128C/256T; Up to 504MB Cache per CPU E-cores: Up to 288C/288T; Up to 576MB Cache per CPU
Note	Supports up to 500W TDP CPUs (Air Cooled) Supports up to 500W TDP CPUs (Liquid Cooled)

GPU

Max GPU Count	Up to 4 double-width or 8 single-width GPUs
Supported GPU	NVIDIA PCIe: H100 NVL, A16, L4, L40S, NVIDIA RTX PRO™ 4500 Blackwell, NVIDIA RTX PRO™ 6000 Blackwell Max-Q Workstation Edition, RTX 5000 Ada View GPU Options
CPU-GPU Interconnect	PCIe 5.0 x16 CPU-to-GPU Interconnect

System Memory

Memory	Slot Count: 24 DIMM slots Max Memory (1DPC): Up to 6TB 8800MT/s ECC DDR5 MRDIMM (P-core only) Max Memory (1DPC): Up to 6TB 6400MT/s ECC DDR5 RDIMM (P-core) Max Memory (1DPC): Up to 3TB 8000MT/s ECC DDR5 RDIMM (E-core) View Memory Options
Memory Voltage	1.1V

On-Board Devices

NVMe	NVMe; RAID 0/1/5/10 support(Intel® VROC RAID key required) View NVMe Options
Network Connectivity	Via AIOM View AIOM Options View AOC Options

Input / Output

LAN	1 RJ45 1 GbE Dedicated BMC LAN port

USB	2 USB 3.2 Gen1 ports (Rear)
Video	1 VGA port

System BIOS

BIOS Type	AMI 64MB SPI Flash

Management

Software	SuperCloud Composer® (SCC) Supermicro Server Manager (SSM) Super Diagnostics Offline (SDO) Supermicro Thin-Agent Service (TAS) SuperServer Automation Assistant (SAA) New!
Power configurations	Power-on mode for AC power recovery ACPI Power Management

Security

Hardware	Trusted Platform Module (TPM) 2.0 Silicon Root of Trust (RoT) – NIST 800-193 Compliant
Features	Cryptographically Signed Firmware Secure Boot Secure Firmware Updates Automatic Firmware Recovery Supply Chain Security: Remote Attestation Runtime BMC Protections System Lockdown

PC Health Monitoring

CPU	Monitors for CPU Cores, Chipset Voltages, Memory
Fan	Fans with tachometer monitoring Pulse Width Modulated (PWM) fan connectors Status monitor for speed control
Temperature	Monitoring for CPU and chassis environment Thermal Control for fan connectors

Certifications

Operating Systems	Oracle Linux 9.4, RHEL 9.4, RHEL 10.0, SAP HANA 2.0, Windows Server 2025 View all OS Compatibility and Certification Matrix
Enterprise Solutions	SAP HANA

Chassis

Form Factor	2U Rackmount

Model	CSE-HS201-R000NFP

Dimensions and Weight

Height	3.5" (88.9 mm)
Width	17.2" (437 mm)
Depth	31.74" (806.2 mm)
Package	9.96" (H) x 26.46" (W) x 43.31" (D)
Weight	Gross Weight: 75 lbs (34 kg) Net Weight: 45 lbs (20.5 kg)
Available Color	Silver

Front Panel

Buttons	Power On/Off UID button
LED	HDD activity LAN1 activity Power status System information

Expansion Slots

PCI-Express (PCIe) Configuration	Option A*4 PCIe 5.0 x16 FH/10.5"L double-width slots 2 PCIe 5.0 x16 AIOM slots (OCP 3.0 compatible) 4 PCIe 5.0 x16 FH/10.5"L double-width slots 2 PCIe 5.0 x16 AIOM slots (OCP 3.0 compatible) Option B*8 PCIe 5.0 x8 (in x16) FH/10.5"L slots 2 PCIe 5.0 x16 AIOM slots (OCP 3.0 compatible) 8 PCIe 5.0 x8 (in x16) FH/10.5"L slots 2 PCIe 5.0 x16 AIOM slots (OCP 3.0 compatible) (*Requires additional parts, please see the optional parts list for details. For more details on PCIe slot configuration options, please refer to the system callout images above.) View AOC Options
CXL Support	Up to 4 CXL 2.0 x16/x8 devices

Drive Bays / Storage

Drive Bays Configuration	Default: Total 8 bays8 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bays 8 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bays Option A: Total 16 bays16 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bays 16 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bays Option B: Total 24 bays24 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bays 24 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bays (*NVMe/SAS/SATA support may require additional storage controller and/or cables, please see the optional parts list for details) View NVMe Options
M.2	2 M.2 PCIe 5.0 x2 NVMe slots (M-key 2280/22110) View M.2 Options

System Cooling

Fans	Up to 6 counter-rotating 60x60x56mm Fan(s)
Air Shroud	2 Air Shrouds
Liquid Cooling	Direct to Chip (D2C) Cold Plate (optional)

Power Supply

2x 2600W Redundant (1 + 1) Titanium Level (96%) Hot-plug power supplies

Dimension (WxHxL)	73.5 x 40 x 265 mm
Input	2600W: 200-240Vac / 50-60Hz 2600W: 200-240Vdc / 50-60Hz (for CQC only)
+12V	Max: 216A / Min: 0A (200Vac-240Vac)
12V SB	Max: 3.5A
Output Type	Backplanes (gold finger)

2x 1600W Redundant (1 + 1) Titanium Level (96%) Hot-plug power supplies

Dimension (WxHxL)	73.5 x 40 x 265 mm
Input	1000W: 100-127Vac / 50-60Hz 1600W: 200-240Vac / 50-60Hz 1600W: 200-240Vdc / 50-60Hz (for CQC only)
+12V	Max: 83.3A / Min: 0A (100Vac-127Vac) Max: 133.3A / Min: 0A (200Vac-240Vac)
12V SB	Max: 3.5A
Output Type	Backplanes (gold finger)

2x 2000W Redundant (1 + 1) Titanium Level (96%) Hot-plug power supplies

Dimension (WxHxL)	73.5 x 40 x 265 mm

Input	1000W: 100-127Vac / 50-60Hz 1800W: 200-220Vac / 50-60Hz 1980W: 220-230Vac / 50-60Hz 2000W: 230-240Vac / 50-60Hz 2000W: 220-240Vac / 50-60Hz (for UL only) 2000W: 230-240Vdc / 50-60Hz (for CQC only)
+12V	Max: 83A / Min: 0A (100Vac-127Vac) Max: 150A / Min: 0A (200Vac-220Vac) Max: 165A / Min: 0A (220Vac-230Vac) Max: 166A / Min: 0A (230Vac-240Vac)
12V SB	Max: 3.5A / Min: 0A
Output Type	Backplanes (gold finger)

Operating Environment

Environmental Spec.	Name: A2 Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -30°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 80% (max 21° DP; non-condensing) Non-operating Relative Humidity: 8% to 90% (max 38° DP; non-condensing)